

Reliability Statistics

- 1) C. M. Tan and N. Raghavan. “Unveiling the electromigration physics of ULSI interconnects through statistics,” Semiconductor Science and Technology, vol. 22, no. 8, pp. 941-946, 2007.
- 2) G. Zhang, C. M. Tan, K. T. Tan, K. Y. Sim, and W. Y. Zhang. “Reliability improvement in Al metallization: a combination of statistical prediction and failure analytical methodology,” Microelectronics Reliability, vol. 44, no. 9-11, pp. 1843-1848, 2004.
- 3) C. M. Tan and K. N. C. Yeo. “A reliability statistics perspective on the pitfalls of standard wafer-level electromigration accelerated test (SWEAT),” Journal of Electronic Testing-Theory and Applications, vol. 17, no. 1, pp. 63-68, 2001.